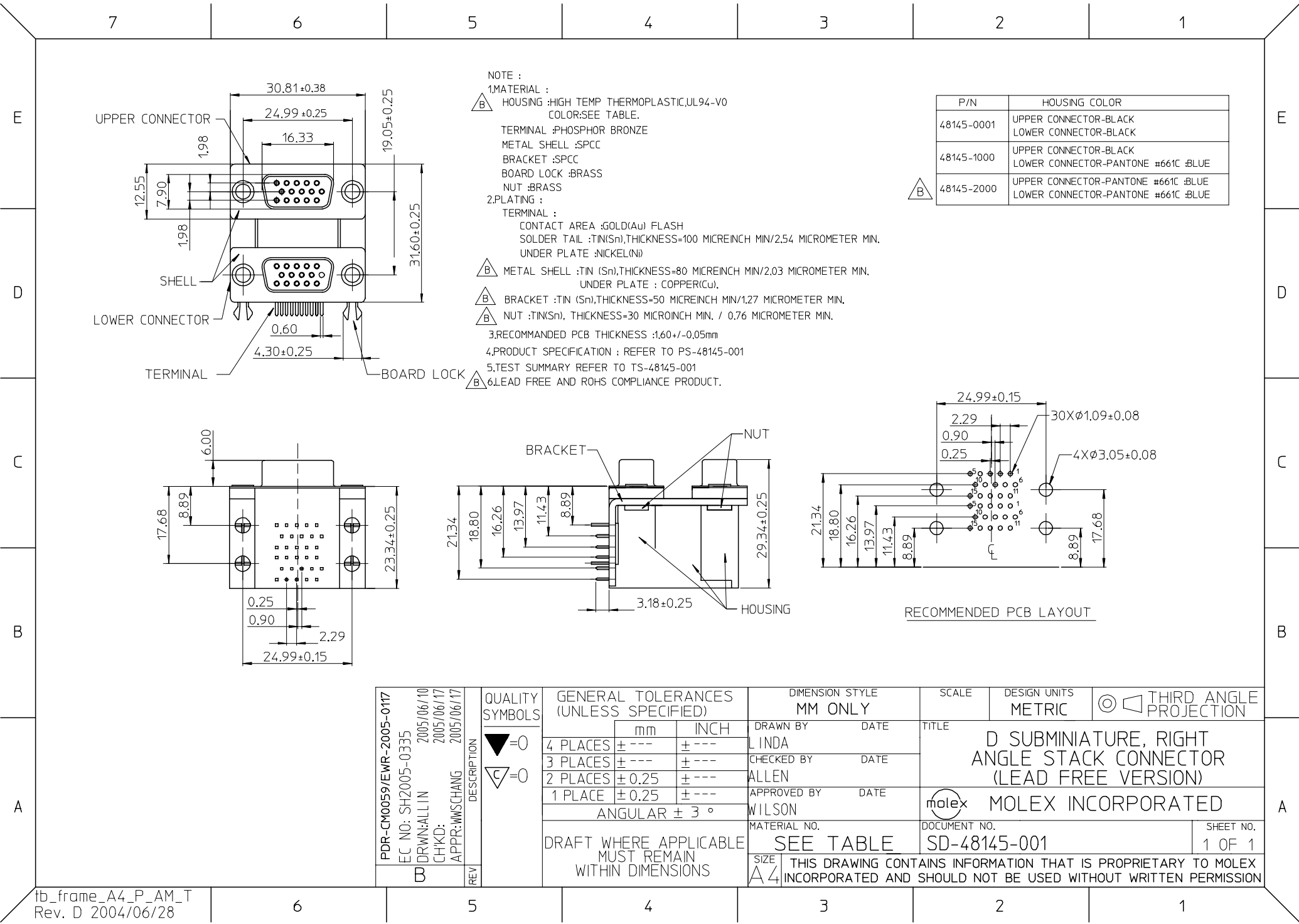




NOTE :

1.MATERIAL :
B HOUSING :HIGH TEMP THERMOPLASTIC,UL94-V0
COLOR:SEE TABLE.

TERMINAL :PHOSPHOR BRONZE
METAL SHELL :SPCC
BRACKET :SPCC
BOARD LOCK :BRASS
NUT :BRASS

2.PLATING :

TERMINAL :
CONTACT AREA :GOLD(Au) FLASH
SOLDER TAIL :TIN(Sn),THICKNESS=100 MICREINCH MIN/2.54 MICROMETER MIN.
UNDER PLATE :NICKEL(Ni)

B METAL SHELL :TIN (Sn),THICKNESS=80 MICREINCH MIN/2.03 MICROMETER MIN.
UNDER PLATE : COPPER(Cu).

B BRACKET :TIN (Sn),THICKNESS=50 MICREINCH MIN/1.27 MICROMETER MIN.

B NUT :TIN(Sn), THICKNESS=30 MICROINCH MIN. / 0.76 MICROMETER MIN.

3.RECOMMENDED PCB THICKNESS :1.60+/-0.05mm

4.PRODUCT SPECIFICATION : REFER TO PS-48145-001

5.TEST SUMMARY REFER TO TS-48145-001

B 6.LEAD FREE AND ROHS COMPLIANCE PRODUCT.

P/N	HOUSING COLOR
48145-0001	UPPER CONNECTOR-BLACK LOWER CONNECTOR-BLACK
48145-1000	UPPER CONNECTOR-BLACK LOWER CONNECTOR-PANTONE #661C :BLUE
B 48145-2000	UPPER CONNECTOR-PANTONE #661C :BLUE LOWER CONNECTOR-PANTONE #661C :BLUE

B

RECOMMENDED PCB LAYOUT

PDR-CM0059/EWR-2005-0117				DESCRIPTION REV	QUALITY SYMBOLS ▽=0 □=0	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION				
EC NO: SH2005-0335		2005/06/10						mm		INCH		DRAWN BY		DATE		TITLE D SUBMINIATURE, RIGHT ANGLE STACK CONNECTOR (LEAD FREE VERSION)	
DRWN:ALLIN		2005/06/17				4 PLACES		± ---		± ---		LINDA		DATE			
CHKD:		2005/06/17				3 PLACES		± ---		± ---		CHECKED BY		DATE			
APPR:WWSCHANG		2005/06/17				2 PLACES		± 0.25		± ---		ALLEN				MOLEX MOLEX INCORPORATED	
						1 PLACE		± 0.25		± ---		APPROVED BY		DATE			
												WILSON					
										ANGULAR ± 3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
										DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-48145-001		1 OF 1	
										SIZE A4		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					